

Now available on-line—CINDAS Microelectronics Packaging Materials Database (MPMD)

The Microelectronics Packaging Materials Database (MPMD) is a searchable, browsable on-line database that contains data about thermal, mechanical, electrical and physical properties of microelectronics packaging materials. The MPMD database contains 1,112 materials, 424 properties and contains 24,940 data curves.

The MPMD was developed under the sponsorship of the Semiconductor Research Corporation (SRC). The results of this research program were originally available only to SRC members. Now they are available to engineers and scientists worldwide.

Search and Browse the Microelectronics Packaging Materials Data- base by

Material Group
(Adhesives, Ceramics, Unfilled Epoxies, Semiconductors, etc.)
Material Name
(Silver-Filled Epoxy, Iron Aluminides Intermetallics, Germanium, etc.)
Property Group
(Electrical, Mechanical, Thermophysical, Optical, etc.)
Property Name
(Dielectric Constant, Leakage Conductance, Elastic Modulus, etc.)

Access

Costs of subscriptions to the CINDAS databases depend on the number of locations and the number of potential users at each location. Once subscribed, engineers, librarians, researchers, and scientists all have unlimited access to the databases by IP address/ranges.

Interface Tools

Save – data for further analysis.

Copy – graphs with ease into PowerPoint.

Project and Manipulate – the database content live.

Interface Features

Find – material group or property group by browsing, or material name or property name by searching.

View – the effects on a given property with changes in temperature or other independent variable.

Compare – multiple data curves of different materials on a single graph.

References – are available for every graph and description in the show text feature.

Complete Packages

The most complete package for research and applications includes:

ASMD – Aerospace Structural Metals Database

HPAD – High Performance Alloys Database

AHAD – Aerospace and High Performance Alloys Database (combines ASMD and HPAD)

CLTD – Cryogenic and Low Temperatures Database

TPMD – Thermophysical Properties of Matter Database

MPMD – Microelectronics Packaging Materials Database

The CINDAS databases give the composition and describe the test conditions of each material. They also present specific conditions for each desired material plotted on a graph.

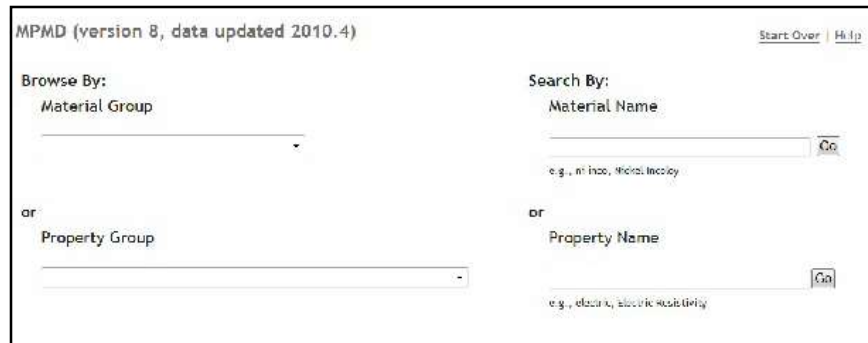
Learn more at <https://cindasdata.com/resources>

Searching and Browsing: Microelectronics Packaging Materials Database (MPMD) Finding Information

Search: Enter the full or partial name of the property or material.

Browse: Use the drop-down menu to find the property or material.

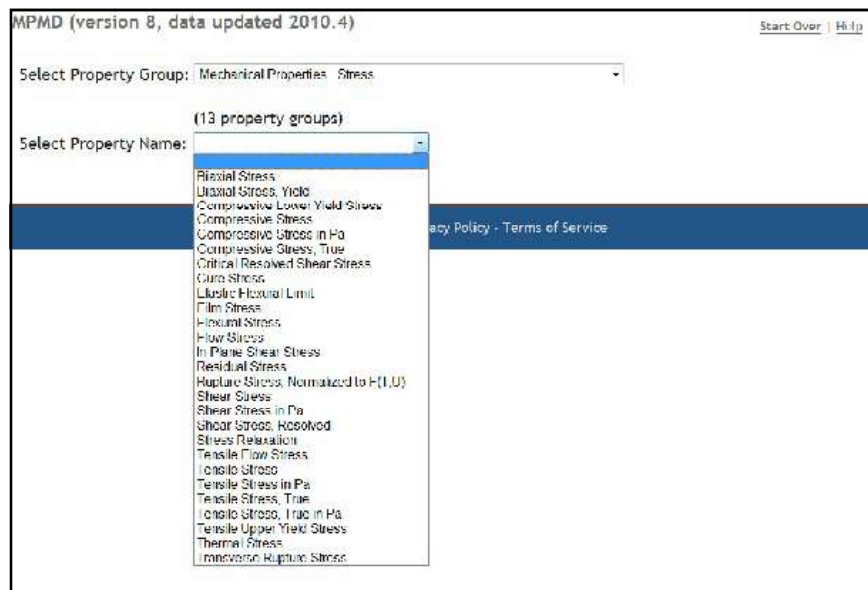
The Microelectronics Packaging Materials Database contains 1,112 materials in 25 material groups and 424 properties in 13 property groups.



MPMD (version 8, data updated 2010.4) [Start Over](#) [Help](#)

Browse By:
Material Group
or
Property Group

Search By:
Material Name
e.g., ni inco, nickel incoy
Go
or
Property Name
e.g., elastic, electric resistivity
Go



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Select Property Group: Mechanical Properties Stress

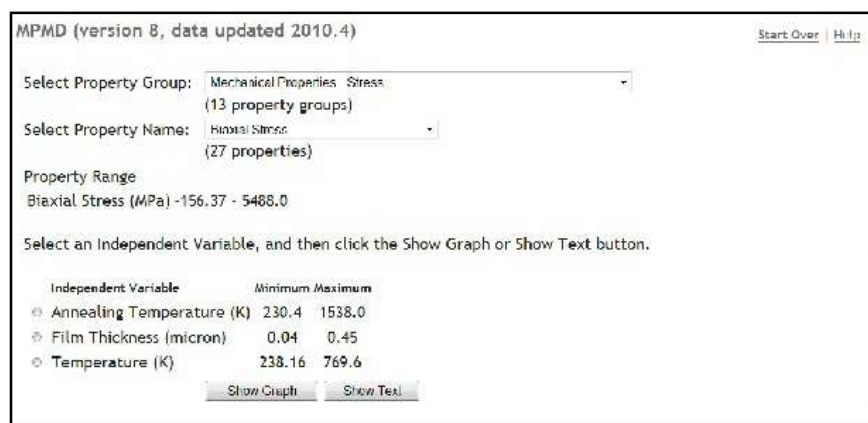
(13 property groups)

Select Property Name:
Biaxial Stress
Dilational Stress, Yield
Compressive Lower Yield Stress
Compressive Stress
Compressive Stress in Pa
Compressive Stress, True
Critical Resolved Shear Stress
Cure Stress
Elastic Flexural Limit
Film Stress
Flexural Stress
Flow Stress
In Plane Shear Stress
Residual Stress
Rupture Stress, Normalized to H(T,U)
Shear Stress
Shear Stress in Pa
Shear Stress, KcsMod
Stress Relaxation
Tensile Flow Stress
Tensile Stress
Tensile Stress in Pa
Tensile Stress, True
Tensile Stress, True in Pa
Tensile Upper Yield Stress
Thermal Stress
Tensile Rupture Stress

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Customizing Information

Select: The independent variable.



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Select Property Group: Mechanical Properties Stress
(13 property groups)

Select Property Name: Biaxial Stress
(27 properties)

Property Range
Biaxial Stress (MPa) -156.37 - 5488.0

Select an Independent Variable, and then click the Show Graph or Show Text button.

Independent Variable	Minimum	Maximum
⊗ Annealing Temperature (K)	230.4	1538.0
⊗ Film Thickness (micron)	0.04	0.45
⊗ Temperature (K)	238.16	769.6

[Show Graph](#) [Show Text](#)

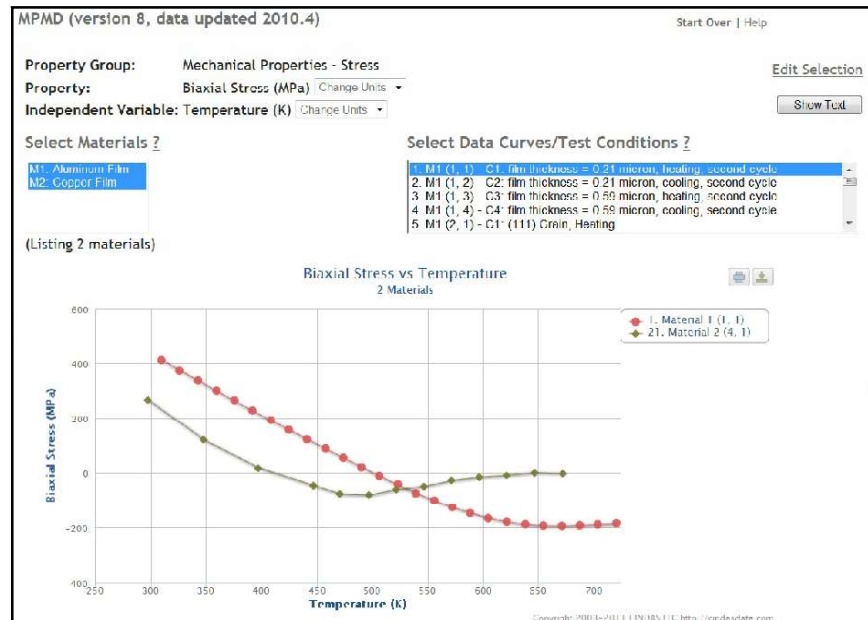
Viewing Information

The MPMD allows the user to view a property of multiple materials on one graph.

Step 1: Select Materials.

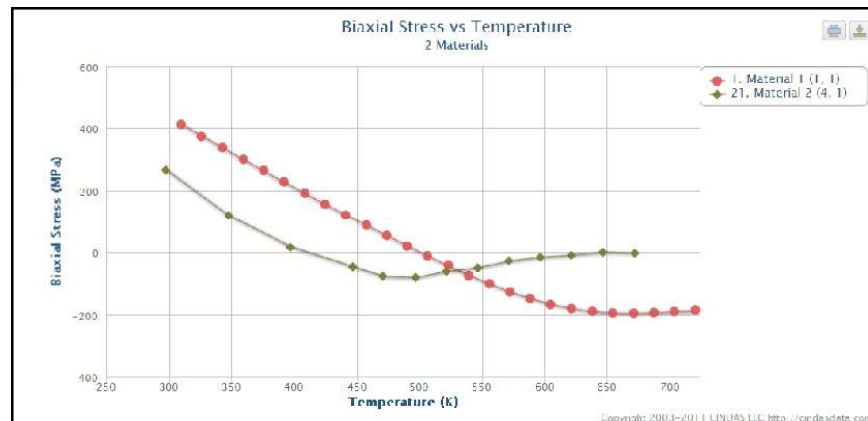
Step 2: Select Data Curves or Test Conditions.

Note: At any time, the user can click on the "Show Text" button to see the values of the data points, text description, references, etc.



Results: Graphic and Numeric

- 24,940 data curves
- Color-coded data curves
- Multiple curves of different materials per graph
- Hovering cursor to show X and Y values at each data point
- Unit conversion package
 - Contains both English and SI units
 - Shows all typically used units for the variables
 - Allows both X-axis and Y-axis selection



Material Groups

The MPMD has 1,112 materials classified into 25 material groups. The MPMD can be searched by material or property name. If the full name is used to search, the search will bring the user directly to that material. If a partial name is used, the search will return the closest matches.

Material Groups	Number
Adhesives	30
Ceramics - High K Oxides	33
Ceramics - Nitrides, Silicides, Carbides,...	30
Ceramics - Others	22
Ceramics - Oxides	34
Cermets	3
Coating and Unfilled Epoxies	25
Composites - Laminates	126
Composites - Laminates (Glass/Epoxy)	74
Composites - Others	51
Composites - Thermal Management	46
Compounds, Molding	55
Elements	33
Encapsulants and Underfill Materials	27
Intermetallics, Aluminides	66
Intermetallics, Beryllides	35
Intermetallics, Miscellaneous	50
Intermetallics, Silicides	30
Liquids & Gases	5
Metal Alloys	58
Polymers - Others	23
Polymers - Polyimides	54
Semiconductors & Optical/Sensor Materials	59
Solders - Lead Free	57
Solders - Lead	41

Property Groups

The MPMD contains 424 different properties. These properties are separated into 13 easy-to-navigate property groups. Alternatively, you can search the property names by using keywords which would bring you directly to the property you are seeking.

Property Type	Number
Thermophysical Properties	43
Thermoradiative Properties	11
Electrical Properties	44
Mechanical Properties - Modulus	52
Mechanical Properties - Strength	45
Mechanical Properties - Stress	32
Mechanical Properties - Hardness	9
Mechanical Properties - Fatigue	9
Mechanical Properties - Creep	9
Mechanical Properties - Strain, Deformation, Strain rate, Area reduction	39
Mechanical Properties - Others	45
Optical Properties	20
Other Properties	64

We Are Confident in Our Products

The MPMD is quick, efficient, and frequently updated, and is currently used by a growing list of universities, corporations and research facilities. Please visit www.cindasdata.com for a demo.